

applying mechanical forces to fracture the solid bridges.

14. The method for producing a thin film according to claim 13, further comprising applying energy to the first substrate.

15. The method for producing a thin film according to claim 14, wherein applying energy comprises applying thermal energy.

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16. The method for producing a thin film according to claim 14, wherein applying energy comprises applying energy after introducing ions.

17. A method for producing a thin film comprising:
providing a first substrate having a face surface;
introducing ions into the first substrate at the face surface and forming microcavities in the first substrate, wherein the microcavities define a thin film layer extending from the first surface to the microcavities, and wherein the microcavities reside between solid bridges of the first substrate;
bonding a second substrate to the face surface of the first substrate; and
applying mechanical forces to fracture the solid bridges.

18. The method for producing a thin film according to claim 17, further comprising applying energy to the first substrate.

19. The method for producing a thin film according to claim 17, wherein applying energy comprises applying thermal energy.

20. The method for producing a thin film according to claim 17, wherein applying energy comprises applying energy after introducing ions.--